

ELECTRICAL:

CONTACT RESISTANCE:
 20 milliohms MAX at 1 amp. DC.
 INSULATION RESISTANCE:
 5,000 megohms MIN at 500VDC.
 DIELECTRIC WITHSTANDING VOLTAGE:
 800VAC/RMS at 60Hz for one minute.
 VOLTAGE RATING:
 800VAC/RMS at 60Hz.
 CURRENT RATING:
 1.0 amps. per contact.

MECHANICAL:

INSERTION FORCE: 230 grams MAX. per contact pair.
 WITHDRAWAL FORCE: 15 grams MAX. per contact pair.
 CONTACT RETENTION: 680 grams MAX. per contact pair.
 DURABILITY:
 200 mating/unmating cycles MIN. at flash gold over 0.76 micrometers MIN. of palladium/nickel
 50 mating/unmating cycles MIN. at flash gold plating;
 100 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating;
 200 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating.

ENVIRONMENTAL:

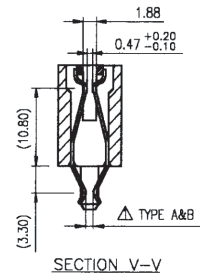
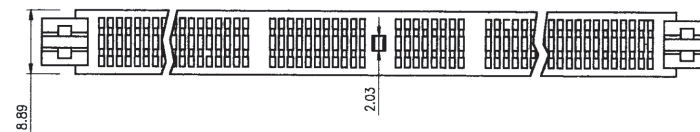
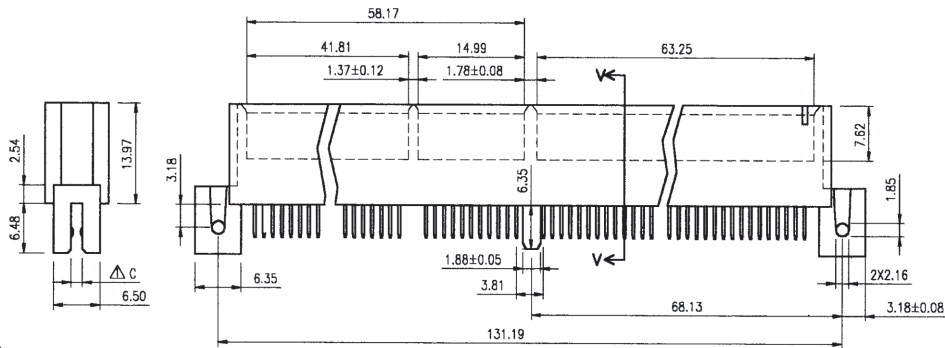
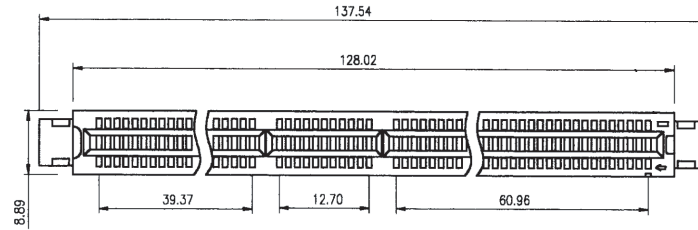
OPERATING TEMPERATURE: -55°C to +105°C
 HUMIDITY: per MIL-STD-1334A, method 1002.1, test condition B
 THERMAL SHOCK: per MIL-STD-1334A, method 1003.1, test condition A
 VIBRATION: per MIL-STD-1334A, method 2005.1, test condition II
 MECHANICAL SHOCK: per MIL-STD-1334A, method 2004.1, test condition C
 SALT SPRAY: 24 hours per MIL-STD-1334A, method 1001.1, test condition

MATERIAL:

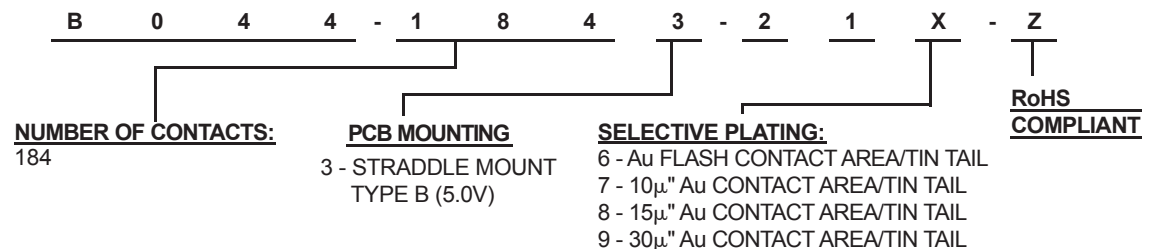
INSULATOR:
 glass-filled thermoplastic (PPS/NYLON-66/PBT), UL-94V-0 rated.
 color-white, for PCI connector

CONTACT:

phosphor bronze, per ASTM-B103
 Mating area - selective gold over 1.27 micrometers MIN. of nickel,
 or flash gold over 0.76 micrometers MIN. of nickel
 Termination area - 2.54 micrometers MIN. of tin/lead over
 1.27 micrometers MIN. of nickel



HOW TO ORDER:



Rev		Apv.	Date
0	Issued	MDH	10/04/04
A	Revised for RoHS Compliance	WHS	5/24/06
SCALE	MAT'L	FINISH	
TOL. DEC.	.X +/- 0.25	.XX +/- 0.15	.XXX +/- 0.08
		ANGLE +/- 0.50°	UNIT: mm

SMP TECHNOLOGY, INC.	
Card Edge Connector, 184 Position, 1.27mm Pitch.	
Straddle Mount, Type B (5.0V)	
P/N: B044-1843-21X-Z	Pg: 1